

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t6656bidc-2.5#trmpbf

(Engineering Calculation)

DFN 2mm X 2mm Exp. Pad

(printed on: 2020-07-11 17:44:43)

TOTAL MASS (g) : 0.00911

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000567 | 1000000 | 62237.078125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.002935 | 975000 | 322161.9375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000072 | 24000 | 7903.12158203 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 109.765571594 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000002 | 700 | 219.531143188 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.003010 | 1000000 | 330394.34375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000136 | 1000000 | 14963.7695312 | | |
| | | External Plating Total: | | | | 0.000136 | 1000000 | 14963.7695312 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000072 | 1000000 | 7903.12158203 | | |
| | | Internal Plating Total: | | | | 0.000072 | 1000000 | 7903.12158203 |
| Die Attach | ELECTRICALLY INSULATING ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000005 | 50000 | 548.827819824 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000027 | 300000 | 2963.67041016 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000059 | 650000 | 6476.16845703 | | |
| Die Attach Total: | | | | 0.000091 | 1000000 | 9988.66699219 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000677 | 130000 | 74311.2890625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.004481 | 860000 | 491859.5 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000052 | 10000 | 5707.80957031 | | |
| | | Encapsulation Total: | | | | 0.005210 | 1000000 | 571878.625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000024 | 1000000 | 2634.3737793 | | |
| | | | | | TOTAL MASS (g) : | 0.00911 | | |